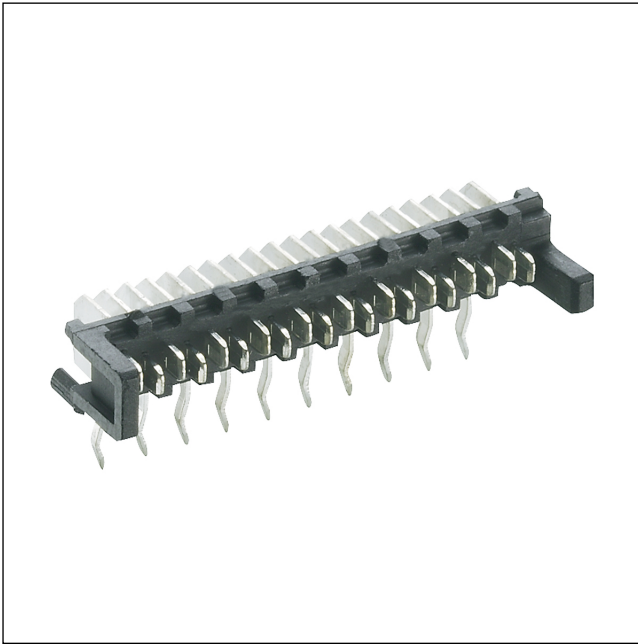


30 MICSW

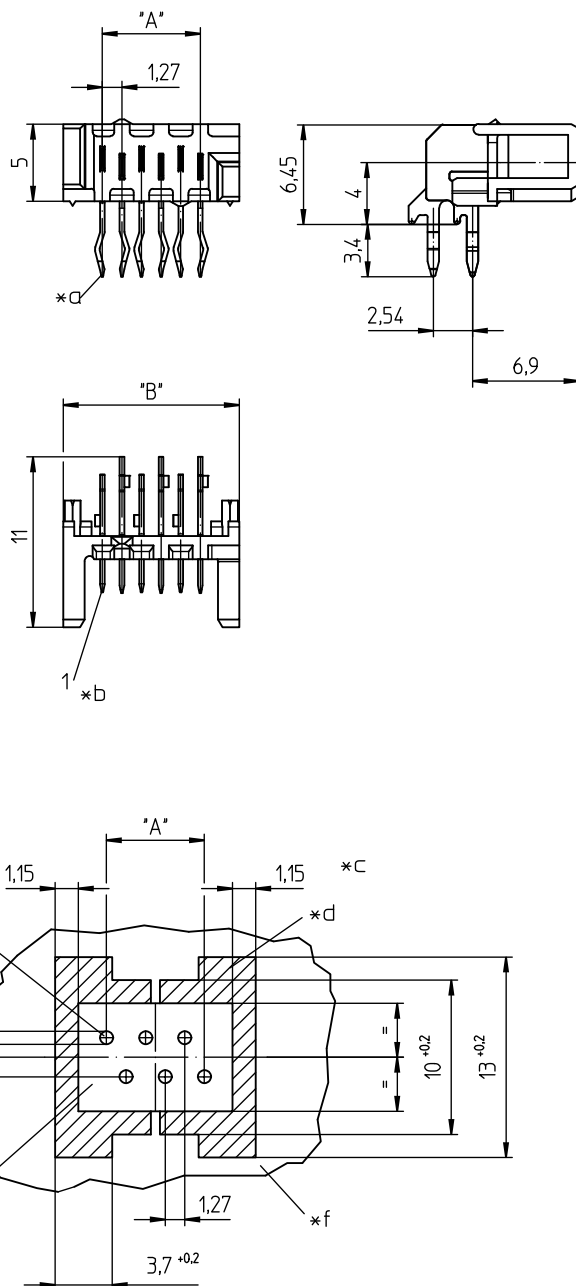
Micromodul™ connectors, pitch 1.27 mm



Micromodul™ tab header, angular, solder contacts dual row staggered

State: Active

30 MICSW



- *a cranked solder contacts
- *b contact 1
- *c printed circuit board layout, solder side view
- *d necessary space for use of pull-off tongs AZ30
- *e component area (B x 7)
- *f recommended thickness of circuit board 1.5 ± 0.14 mm

Environmental conditions

Temperature range -40 °C/+140 °C¹

¹ upper limit temperature (insulating body) RTI (electrical) of the UL Yellow Card

Materials

Insulating body PA GF, V-0 according to UL94
Contact tab CuZn, pre-nickel and tin-plated – MICSW
CuZn, pre-nickel and gold-plated – MICSW AU

Mechanical data

Expression force contact tab from insulating body ≥ 7 N/contact

Electrical data (at T_{amb} 20 °C)

Rated current 1,2 A
Rated voltage 160 V AC
(250 V AC ohne Berücksichtigung der Kriech- und Luftstrecken nach IEC 60664/DIN EN 60664)
Material group I (IEC)/0 (UL) (CTI ≥ 600)
Creepage distance 0,97 mm
Clearance 0,97 mm
Insulation resistance > 1 GΩ

30 MICSW

Designation	Pole Number	PU (Pieces)	MDQ (Pieces)	Dimensions	
				A (mm)	B (mm)
MICSW 04	4	1000	2000	3.81	8.86
MICSW 06	6	1000	2000	6.35	11.40
MICSW 08	8	1000	2000	8.89	13.94
MICSW 10	10	1000	2000	11.43	16.48
MICSW 12	12	500	2000	13.97	19.02
MICSW 14	14	500	2000	16.51	21.56
MICSW 16	16	500	1000	19.05	24.10
MICSW 18	18	500	1000	21.59	26.64
MICSW 20	20	500	1000	24.13	29.18
MICSW 26	26	500	1000	31.75	36.80
MICSW 04 0,8 AU	4	1000	2000	-	-
MICSW 10 0,8 AU	10	1000	2000	-	-

Packaging:

in bulk, in a cardboard box